

Customer No.: 31561
Application No.: 10/605,602
Docket NO.: 10233-US-PA

AMENDMENT

Please amend the application as indicated hereafter.

In the Claims :

1. (original) A method of bonding a heat sink to a chip package structure, wherein the chip package structure at least comprises a chip and a stiffener ring around the chip with the stiffener ring set up over a substrate, and the heat sink comprises a first protruding section located at a position corresponding to the chip and a plurality of second protruding sections located at positions corresponding to the stiffener ring, the method comprising the steps of:

forming a gluing layer over the first protruding section and the second protruding sections of the heat sink; and

bonding the heat sink to the chip package structure such that the first protruding section of the heat sink is attached to the chip and the second protruding sections of the heat sink are attached to the stiffener ring.

2. (original) The method of claim 1, wherein the process of forming a gluing layer over both the first protruding section and the second protruding sections comprising the steps:

providing a gluing tape, wherein the gluing tape comprises a cutting pattern with a shape that matches with the first protruding section and the second protruding sections of the heat sink;

aligning the first protruding section and the second protruding section of the heat

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sink with the cutting pattern and disposing the heat sink onto the gluing tape; and

detaching the heat sink from the gluing tape so that a portion of the gluing tape remains adhered to the first and the second protruding sections to form the gluing layer.

3. (original) The method of claim 2, wherein the gluing tape comprises a heat-softening double-sided adhesive tape.

4. (original) The method of claim 2, wherein the gluing tape comprises a partially polymerized B-stage adhesive film.

5. (original) The method of claim 1, wherein a material constituting the heat sink comprises copper.

6. (original) The method of claim 1, wherein the first protruding section and the second protruding sections are formed together with the heat sink into an integral unit.

7. (original) The method of claim 1, wherein the sum area of all the second protruding sections is less than the area of the stiffener ring.

8. (original) The method of claim 1, wherein the step of bonding the heat sink to the chip package structure further comprises performing a curing operation

Claims 9-20 (canceled).